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Cautions

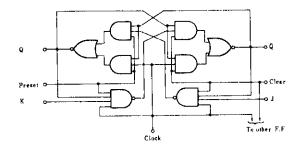
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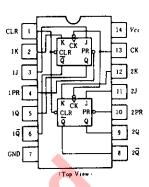
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■BLOCK DIAGRAM (½)



PIN ARRANGEMENT



■RECOMMENDED OPERATING CONDITIONS

Item Clock frequency		Symbol	min	typ	max	Unit	
		felock	0	_	30	MHz	
Pulse	Clock High		20	_	-	ns	
width	Preset Low	iw	25	_		ns	
Setup	"H"Data		20↓	_		ns	
time	"L"Data	tsu	20↓			ns	
Hold time		th	0↓	_	-	ns	

Note) 1; The arrow indicates the falling edge.

FUNCTION TABLE

Inputs					Outputs		
Preset	Clear	Clock	J	K	Q	Q	
L	H	×	×	×	Н	L	
Н	L	×	×	×	L	Н	
L	L	×	×	×	H*	Н*	
H	Н		L	L	Qσ	Qσ	
Н	H	1	н	L	Н	L	
Н	H	1	L	Н	L	Н	
H	H	1	Н	H	Toggle		
H	Н	Н	×	×	Qο	Qσ	

Notes) H; high level, L; low level, X; irrelevant

1; transition from high to low level

 \mathbf{Q}_{o} ; level of Q before the indicated steady-state input conditions were established.

Q₀; complement of Q₀ or level of Q before the indicated steady-state input conditions were established.

Toggle; each output changes to the complement of its previous level on each active transition indicated by 1.

*; This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (high) level.

BELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75$ °C)

Item		Symbol	Test Conditions		min	typ*	max	Unit
Input voltage		VIH			2.0			V
		v_{tt}			-		0.8	V
Output voltage		Von	$V_{UC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V, $I_{OH} = -400 \mu$ A		2.7			V
			$V_{CC} = 4.75 \text{V}, V_{IL} = 0.8 \text{V},$	<i>IoL</i> = 8m A	_		0.5	v
		Vol	$V_{IH} = 2V$	$I_{OL} = 4 \mathrm{m}\mathrm{A}$			0.4	v
J, K		1	1		_		20	
	Clear	IIH	$V_{CC} = 5.25 \text{V}, V_t = 2.7 \text{V}$		_	-	120	μΑ
	Preset				_		60	
	Clock				_	160		
	J, K					-0.4	m A	
_	Clear	1			-			-1.6
Input current	Preset	In.**	$V_{CC} = 5.25 \text{V}, V_I = 0.4 \text{V}$		(-)	N. 1	-0.8	mA
	Clock	1		-		-1.6	Ĺ	
	J, K	1	$V_{CC} = 5.25 \text{V}, V_I = 7 \text{V}$		7		0.1	mA
	Clear	Iı			V -	-	0.6	
	Preset				=_		0.3	
	Clock				5. + 0		0.8	
Short circuit output current		los	$V_{CC} = 5.25 \text{V}$		-20	<i>//</i> –	- 100	mА
Supply current ***		lcc	V _{CC} == 5.25V	V 6		4	8	m A
Input clamp voltage		Vik	$V_{CC} = 4.75 \text{V}, I_{IN} = -18 \text{mA}$		2		-1.5	v

SWITCHING CHARACTERISTICS ($V_{cc} = 5V$, $T_a = 25^{\circ}C$)

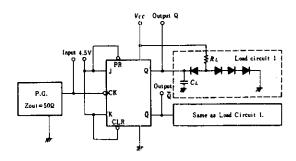
Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum clock frequency	∫max.				30	45		MHz
	tPLH	Clear	Q. Q	$C_L = 15 \text{pF}, R_L = 2 \text{k}\Omega$		11	20	ns
Propagation delay time	TPHL	Preset Clock	Q. Q		_	15	30	ns

VCC = 5V, Ta = 25°C
 ** I_{IL} should not be measured when preset and clear inputs are low at same time.
 *** With all outputs open, ICC is measured with the Q and Q output high in turn. At the time of measurement, the clock input is grounded.

TESTING METHOD

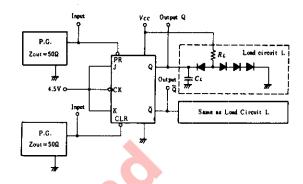
1) Test Circuit

1.1) fmax, tPLH, tPHL (Clock→Q,Q)



- Notes) 1. Test is put into the each flip-flop.
 - 2. All diodes are 1S2074 (B).
 - 3. C_L includes probe and jig capacitance.

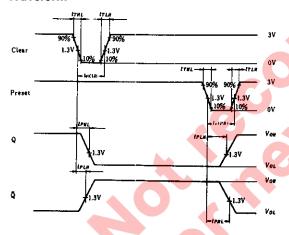
1.2) tPHL, tPLH (Clear, Preset→Q, Q)



- Notes) 1. Test is put into the each flip-flop.
 2. All diodes are 1S2074 .

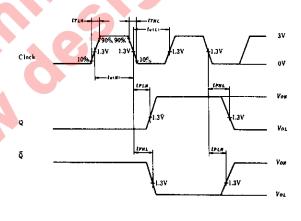
 - 3. CL includes probe and jig capacitance.

Waveform



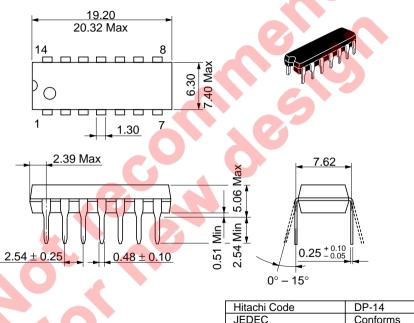
Note) Clock input pulse; $t_{TLH} \leq 5$ ns, $t_{THL} \leq 6$ ns, PRR=1MHz, duty cycle=50% and: for f_{max} , $t_{TLH} = t_{THL} \leq 2.5$ ns.

Waveform



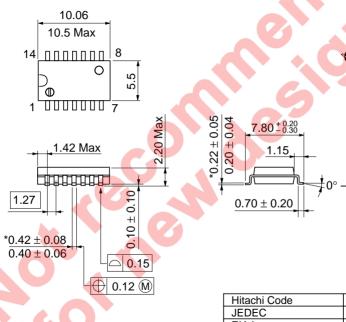
Note) Clear and preset input pulse: $t_{TLH} \le 15 \text{ns}$, $t_{THL} \le 6 \text{ns}$, PRR=1MHz

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

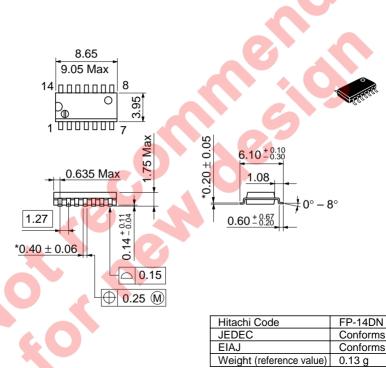
Hitachi Code FP-14DA

JEDEC —

EIAJ Conforms

Weight (reference value) 0.23 g

Unit: mm



*Pd plating

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